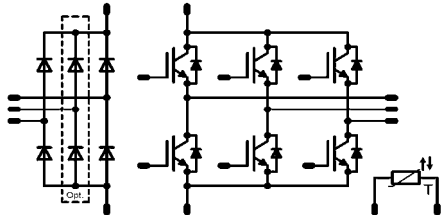


MiniSkiip 0		600V/6A	
Features - Solderless interconnection - Trench Fieldstop IGBT's for low saturation losses - Optional 2- and 3-leg rectifier		Miniskiip0 housing 	
Target Applications - Industrial Drives - Embedded Drives		Schematic 	
Types 80-M006PNB006SA01-K614D, 2-leg rectifier 80-M006PNB006SA-K614C, 3-leg rectifier			

Maximum Ratings

 $T_J=25^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Input Rectifier Diode				
Repetitive peak reverse voltage	V_{RRM}		1600	V
DC forward current	I_{FAV}	$T_J=T_{Jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	25 25	A
Surge forward current	I_{FSM}	$t_p=10\text{ms}$ $T_J=25^{\circ}\text{C}$	220	A
I^2t -value	I^2t		240	A^2s
Power dissipation per Diode	P_{tot}	$T_J=T_{Jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	38 58	W
Maximum Junction Temperature	T_{Jmax}		150	$^{\circ}\text{C}$
Inverter Transistor				
Collector-emitter break down voltage	V_{CE}		600	V
DC collector current	I_C	$T_J=T_{Jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	10 10	A
Repetitive peak collector current	I_{Cpulse}	t_p limited by T_{Jmax}	18	A
Turn off safe operating area		$V_{CE} \leq 1200\text{V}$, $T_J \leq T_{op max}$	18	A
Power dissipation per IGBT	P_{tot}	$T_J=T_{Jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	31 48	W
Gate-emitter peak voltage	V_{GE}		± 20	V
Short circuit ratings	t_{SC} V_{CC}	$T_J \leq 150^{\circ}\text{C}$ $V_{GE}=15\text{V}$	6 360	μs V
Maximum Junction Temperature	T_{Jmax}		175	$^{\circ}\text{C}$

Maximum Ratings

 $T_j=25^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

Inverter Diode

Peak Repetitive Reverse Voltage	V_{RRM}	$T_j=25^{\circ}\text{C}$	600	V
DC forward current	I_F	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	10 10	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	22	A
Power dissipation per Diode	P_{tot}	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$	26 40	W
Maximum Junction Temperature	T_{jmax}		175	$^{\circ}\text{C}$

Thermal Properties

Storage temperature	T_{stg}		-40...+125	$^{\circ}\text{C}$
Operation temperature under switching condition	T_{op}		-40...+($T_{jmax} - 25$)	$^{\circ}\text{C}$

Insulation Properties

Insulation voltage	V_{is}	$t=2s$ DC voltage	4000	V
Creepage distance			min 12,7	mm
Clearance			min 12,7	mm

Characteristic Values

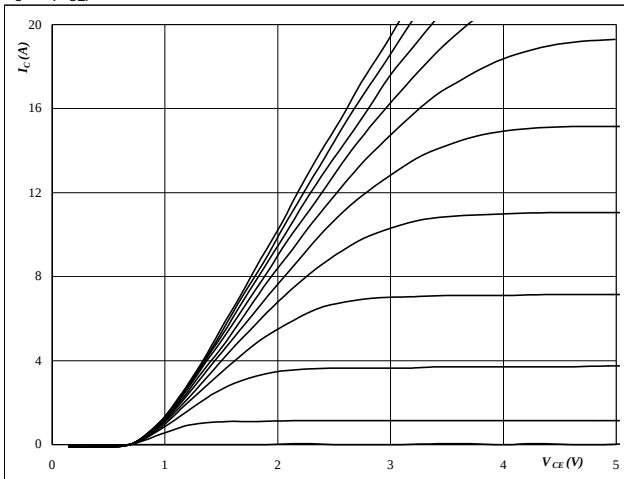
Parameter	Symbol	Conditions					Value			Unit
			V _{GE} [V] or V _{GS} [V]	V _r [V] or V _{CE} [V] or V _{DS} [V]	I _c [A] or I _F [A] or I _o [A]	T _j	Min	Typ	Max	
Input Rectifier Diode										
Forward voltage	V _F				25	T _j =25°C T _j =125°C		1,43 1,44	1,64	V
Threshold voltage (for power loss calc. only)	V _{to}				25	T _j =25°C T _j =125°C		0,92 0,79		V
Slope resistance (for power loss calc. only)	r _t				25	T _j =25°C T _j =125°C		20,29 26,11		mΩ
Reverse current	I _r			1600		T _j =25°C T _j =125°C			0,05	mA
Thermal resistance chip to heatsink per chip	R _{thJH}	Thermal grease thickness≤50um λ = 1 W/mK						1,83		K/W
Inverter Transistor										
Gate emitter threshold voltage	V _{GE(th)}	V _{CE} =V _{GE}			0,00009	T _j =25°C T _j =150°C	5	5,8	6,5	V
Collector-emitter saturation voltage	V _{CE(sat)}		15		6	T _j =25°C T _j =150°C	1,24	1,59 1,84	2,04	V
Collector-emitter cut-off current incl. Diode	I _{CES}		0	600		T _j =25°C T _j =150°C			0,0004	mA
Gate-emitter leakage current	I _{GES}		20	0		T _j =25°C T _j =150°C			300	nA
Integrated Gate resistor	R _{gint}									Ω
Turn-on delay time	t _{d(on)}	R _{goff} =64 Ω R _{gon} =64 Ω	±15	300	6	T _j =25°C T _j =150°C		105 102,4		ns
Rise time	t _r					T _j =25°C T _j =150°C		21,8 27,8		
Turn-off delay time	t _{d(off)}					T _j =25°C T _j =150°C		142,2 163,6		
Fall time	t _f					T _j =25°C T _j =150°C		102,7 132,4		
Turn-on energy loss per pulse	E _{on}								T _j =25°C T _j =150°C	
Turn-off energy loss per pulse	E _{off}				T _j =25°C T _j =150°C		0,15 0,19			
Input capacitance	C _{ies}	f=1MHz	0	25		T _j =25°C		368		pF
Output capacitance	C _{oss}							28		
Reverse transfer capacitance	C _{rss}							11		
Gate charge	Q _{Gate}		15	480	6	T _j =25°C		62	42	nC
Thermal resistance chip to heatsink per chip	R _{thJH}	Thermal grease thickness≤50um λ = 1 W/mK						3,03		K/W
Inverter Diode										
Diode forward voltage	V _F				6	T _j =25°C T _j =150°C		1,42 1,36		V
Peak reverse recovery current	I _{RRM}	R _{gon} =64 Ω	±15	300	6	T _j =25°C T _j =150°C		3,92 5,82		A
Reverse recovery time	t _{rr}					T _j =25°C T _j =150°C		182,7 288,1		ns
Reverse recovered charge	Q _{rr}					T _j =25°C T _j =150°C		0,32 0,77		μC
Peak rate of fall of recovery current	di(rec)max /dt					T _j =25°C T _j =150°C		45 57		A/μs
Reverse recovered energy	E _{rec}					T _j =25°C T _j =150°C		0,06 0,16		mWs
Thermal resistance chip to heatsink per chip	R _{thJH}	Thermal grease thickness≤50um λ = 1 W/mK						3,64		K/W
Thermistor										
Rated resistance	R					T _r =25°C		1000		Ω
Deviation of R	ΔR/R	R25=1000 Ω R100=1670 Ω				T _r =25°C T _r =100°C	-3 -2		3 2	%
R100	R ₁₀₀					T _r =25°C		1670		Ω
Temperature coefficient								0,76		% /K
A-value	B _(25/50)	Tol. %				T _r =25°C		7,635*10-3		1/K
B-value	B _(25/100)	Tol. %				T _r =25°C		1,731*10-5		1/K²
Vincotech NTC Reference									E	

Output Inverter

Figure 1 Output inverter IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

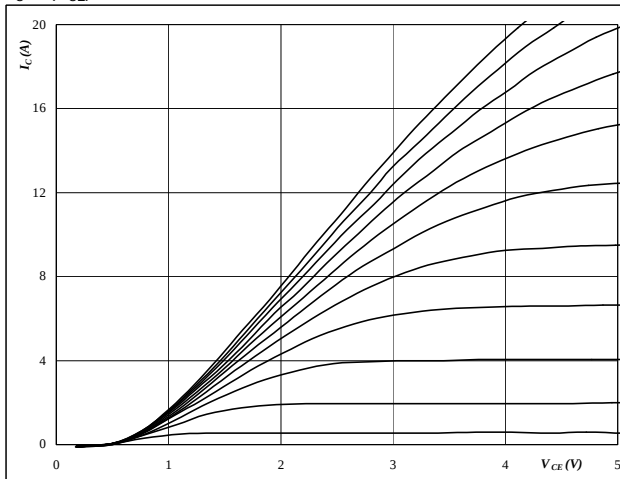


$t_p = 250 \mu s$
 $T_J = 25^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2 Output inverter IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

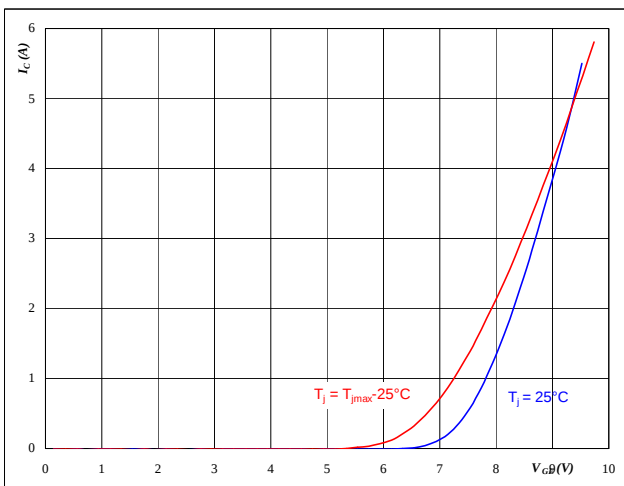


$t_p = 250 \mu s$
 $T_J = 150^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3 Output inverter IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

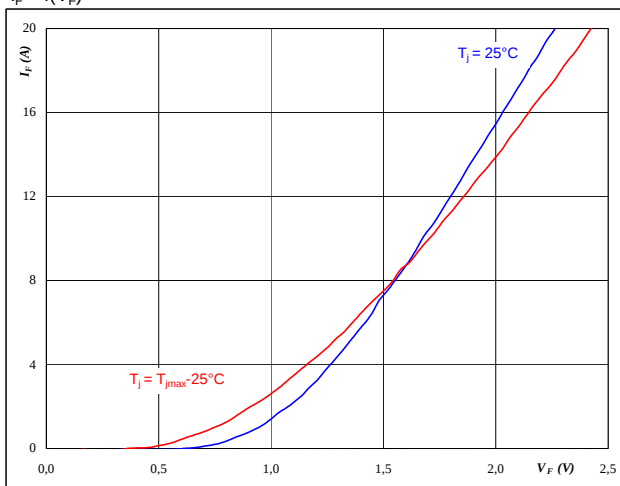


$t_p = 250 \mu s$
 $V_{CE} = 10 V$

Figure 4 Output inverter FWD

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$



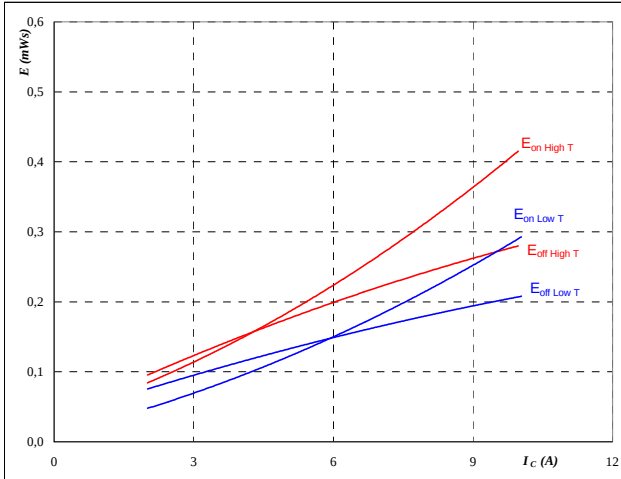
$t_p = 250 \mu s$

Output Inverter

Figure 5 Output inverter IGBT

Typical switching energy losses
as a function of collector current

$$E = f(I_C)$$



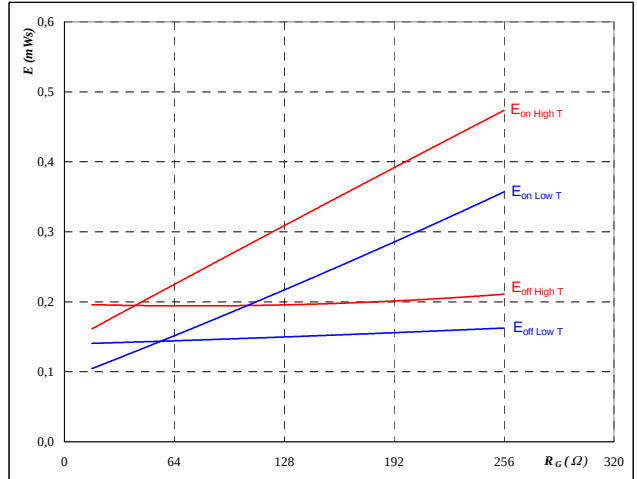
inductive load

$T_J =$	25/150	°C
$V_{CE} =$	300	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω
$R_{goff} =$	64	Ω

Figure 6 Output inverter IGBT

Typical switching energy losses
as a function of gate resistor

$$E = f(R_G)$$



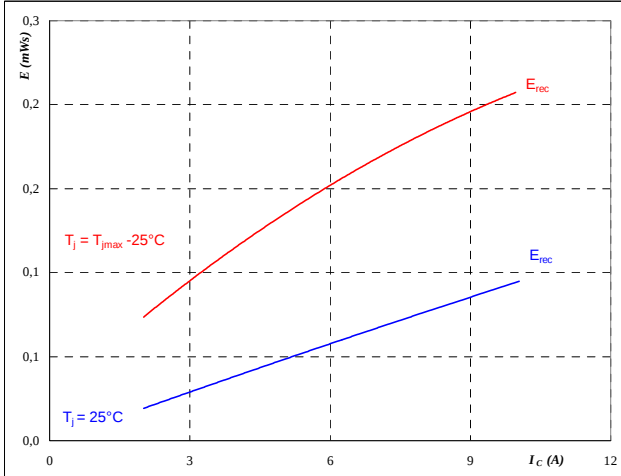
inductive load

$T_J =$	25/150	°C
$V_{CE} =$	300	V
$V_{GE} =$	±15	V
$I_C =$	6	A

Figure 7 Output inverter FWD

Typical reverse recovery energy loss
as a function of collector current

$$E_{rec} = f(I_C)$$



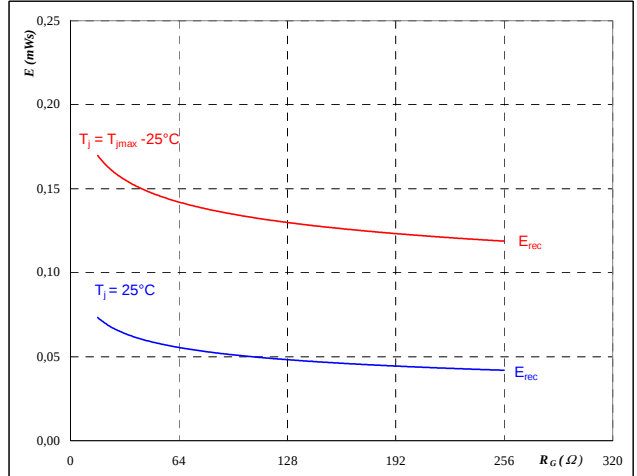
inductive load

$T_J =$	25/150	°C
$V_{CE} =$	300	V
$V_{GE} =$	±15	V
$R_{gon} =$	64	Ω

Figure 8 Output inverter FWD

Typical reverse recovery energy loss
as a function of gate resistor

$$E_{rec} = f(R_G)$$



inductive load

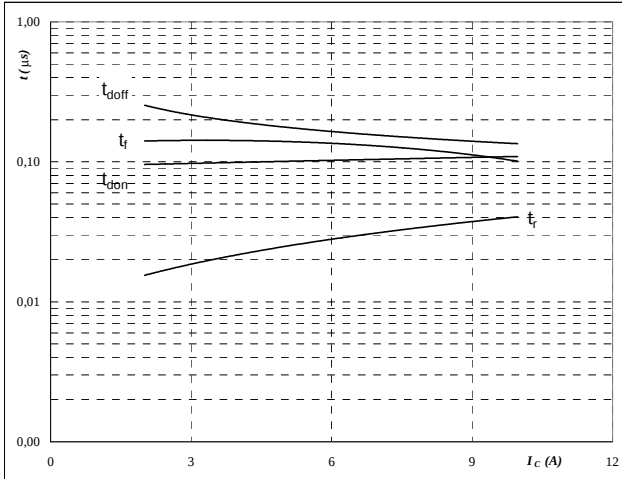
$T_J =$	25/150	°C
$V_{CE} =$	300	V
$V_{GE} =$	±15	V
$I_C =$	6	A

Output Inverter

Figure 9 Output inverter IGBT

Typical switching times as a function of collector current

$t = f(I_C)$



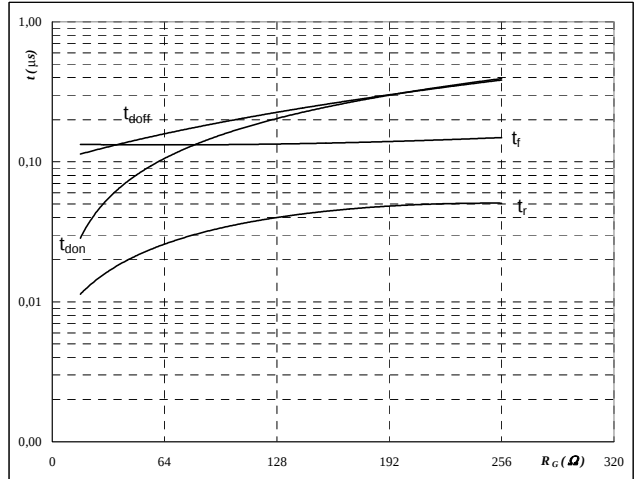
inductive load

$T_J = 150$ °C
 $V_{CE} = 300$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 64$ Ω
 $R_{goff} = 64$ Ω

Figure 10 Output inverter IGBT

Typical switching times as a function of gate resistor

$t = f(R_G)$



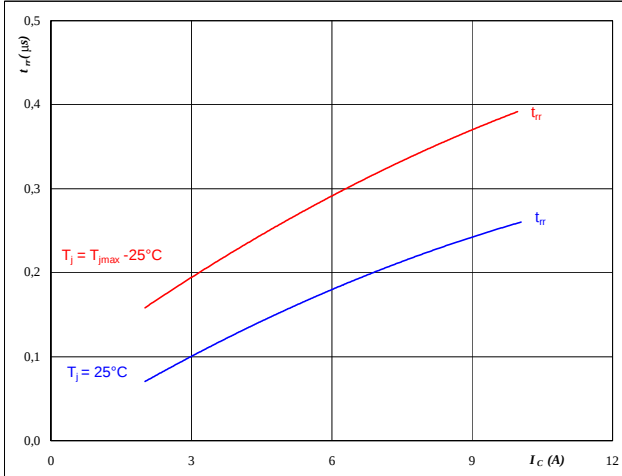
inductive load

$T_J = 150$ °C
 $V_{CE} = 300$ V
 $V_{GE} = \pm 15$ V
 $I_C = 6$ A

Figure 11 Output inverter FWD

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

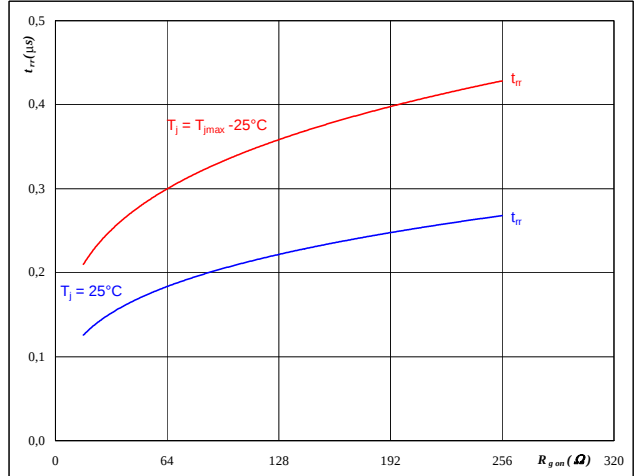


$T_J = 25/150$ °C
 $V_{CE} = 300$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 64$ Ω

Figure 12 Output inverter FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



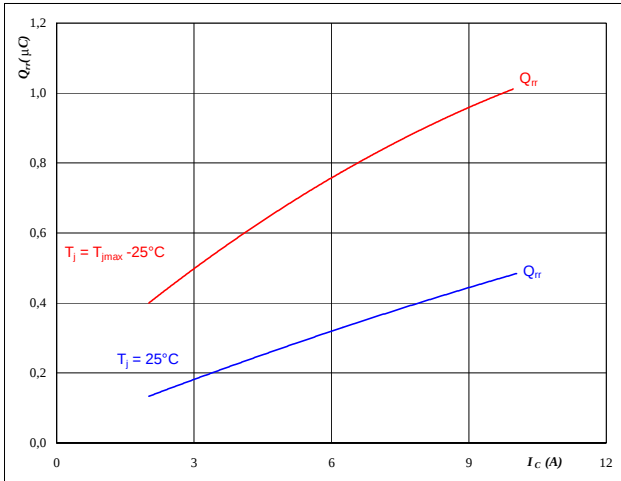
$T_J = 25/150$ °C
 $V_R = 300$ V
 $I_F = 6$ A
 $V_{GE} = \pm 15$ V

Output Inverter

Figure 13 Output inverter FWD

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$

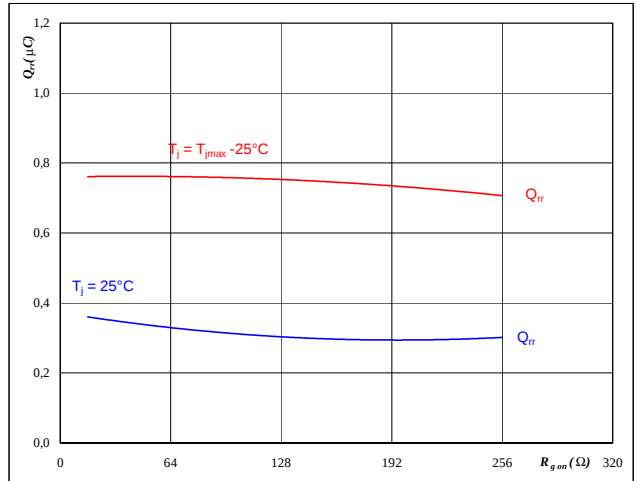


$T_j = 25/150$ °C
 $V_{CE} = 300$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 64$ Ω

Figure 14 Output inverter FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$

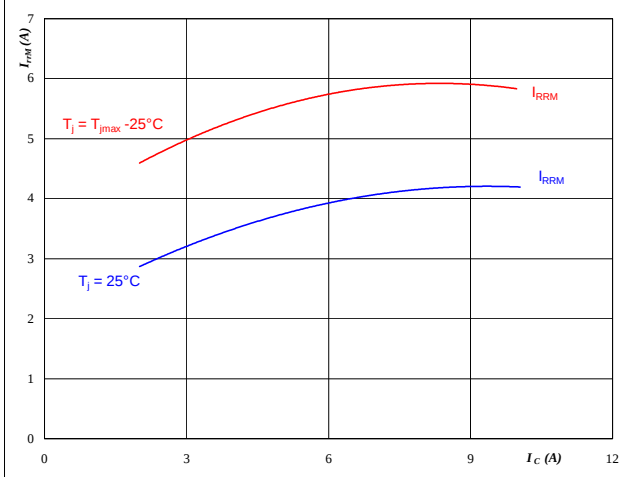


$T_j = 25/150$ °C
 $V_R = 300$ V
 $I_F = 6$ A
 $V_{GE} = \pm 15$ V

Figure 15 Output inverter FWD

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$

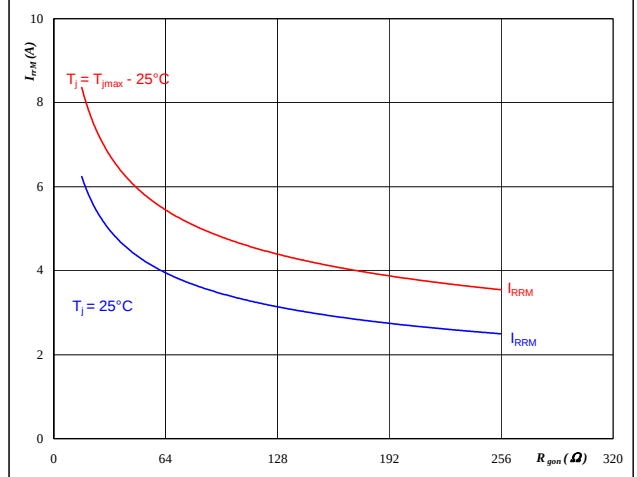


$T_j = 25/150$ °C
 $V_{CE} = 300$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 64$ Ω

Figure 16 Output inverter FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



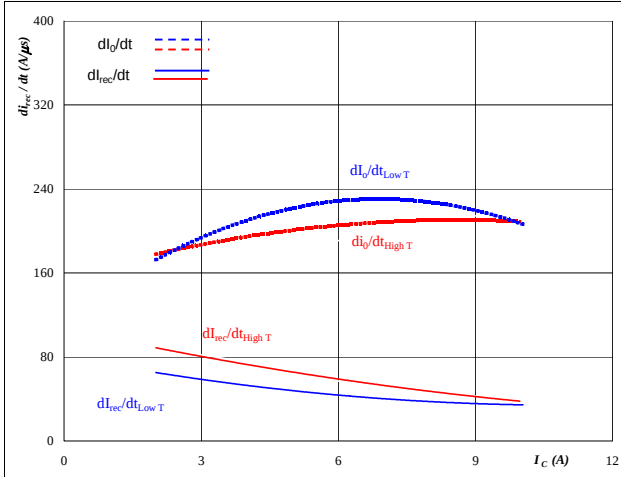
$T_j = 25/150$ °C
 $V_R = 300$ V
 $I_F = 6$ A
 $V_{GE} = \pm 15$ V

Output Inverter

Figure 17 Output inverter FWD

Typical rate of fall of forward
and reverse recovery current as a
function of collector current

$$dI_f/dt, dI_{rec}/dt = f(I_C)$$

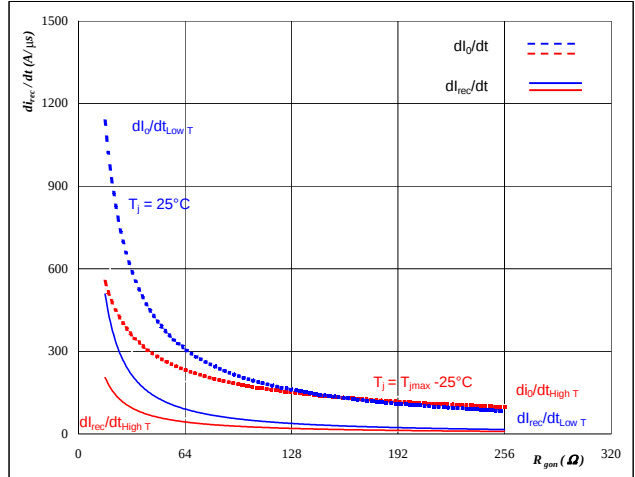


$T_j = 25/150$ °C
 $V_{CE} = 300$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 64$ Ω

Figure 18 Output inverter FWD

Typical rate of fall of forward
and reverse recovery current as a
function of IGBT turn on gate resistor

$$dI_f/dt, dI_{rec}/dt = f(R_{gon})$$

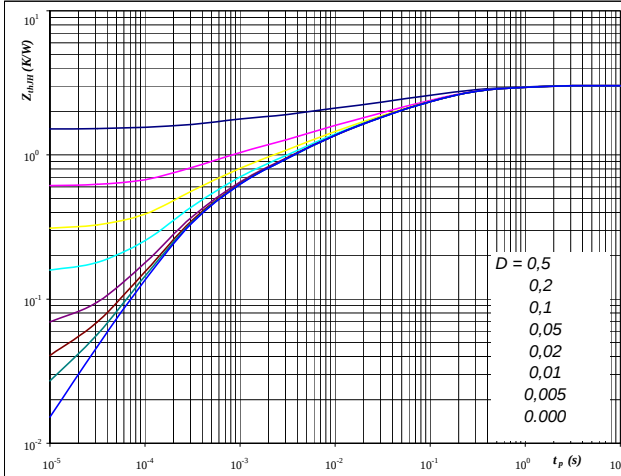


$T_j = 25/150$ °C
 $V_R = 300$ V
 $I_F = 6$ A
 $V_{GE} = \pm 15$ V

Figure 19 Output inverter IGBT

IGBT transient thermal impedance
as a function of pulse width

$$Z_{thJH} = f(t_p)$$



$D = t_p / T$
 $R_{thJH} = 3,03$ K/W 2,46

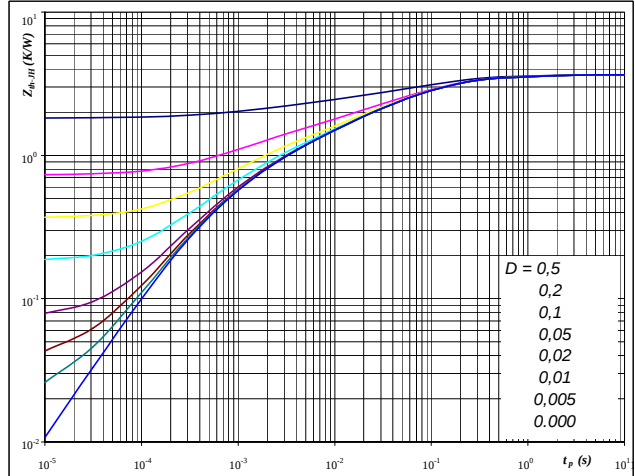
IGBT thermal model values

Thermal grease		Phase change interface	
R (C/W)	Tau (s)	R (C/W)	Tau (s)
0,21	1,1E+00	0,17	9,1E-01
1,04	1,3E-01	0,84	1,1E-01
0,75	2,1E-02	0,61	1,7E-02
0,58	3,1E-03	0,47	2,5E-03
0,44	3,4E-04	0,36	2,8E-04

Figure 20 Output inverter FWD

FWD transient thermal impedance
as a function of pulse width

$$Z_{thJH} = f(t_p)$$



$D = t_p / T$
 $R_{thJH} = 3,64$ K/W 2,95

FWD thermal model values

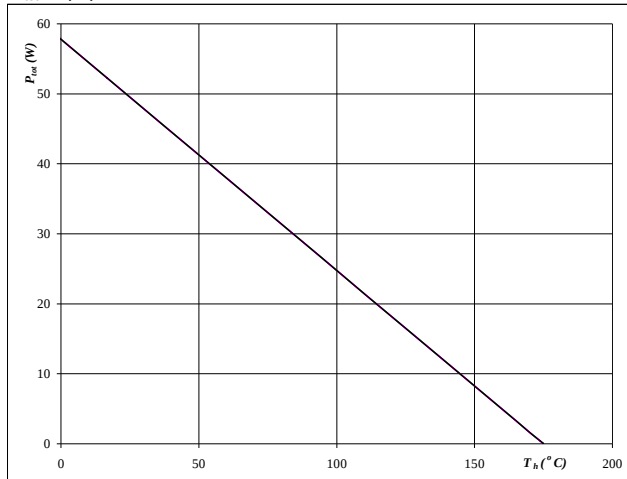
Thermal grease		Phase change interface	
R (C/W)	Tau (s)	R (C/W)	Tau (s)
0,23	1,3E+00	0,18	1,1E+00
1,30	1,3E-01	1,05	1,0E-01
1,10	2,3E-02	0,89	1,8E-02
0,70	2,6E-03	0,57	2,1E-03
0,32	4,2E-04	0,26	3,4E-04

Output Inverter

Figure 21 Output inverter IGBT

Power dissipation as a
function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

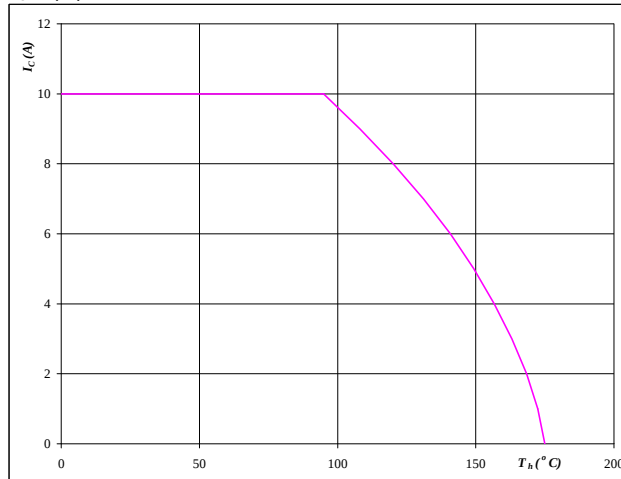


$T_J = 175^{\circ}\text{C}$

Figure 22 Output inverter IGBT

Collector current as a
function of heatsink temperature

$$I_C = f(T_h)$$

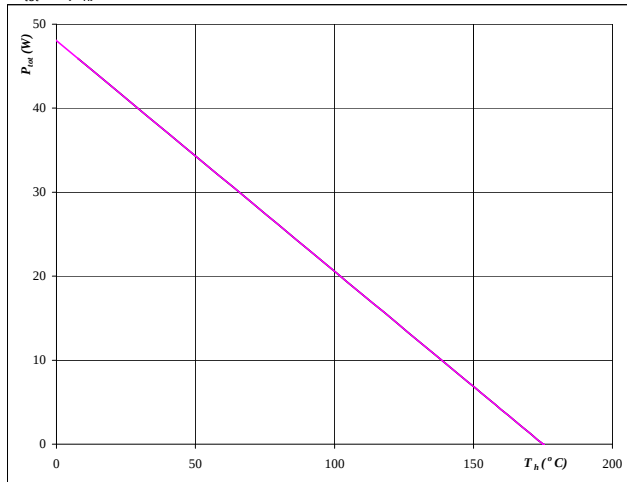


$T_J = 175^{\circ}\text{C}$
 $V_{GE} = 15 \text{ V}$

Figure 23 Output inverter FWD

Power dissipation as a
function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

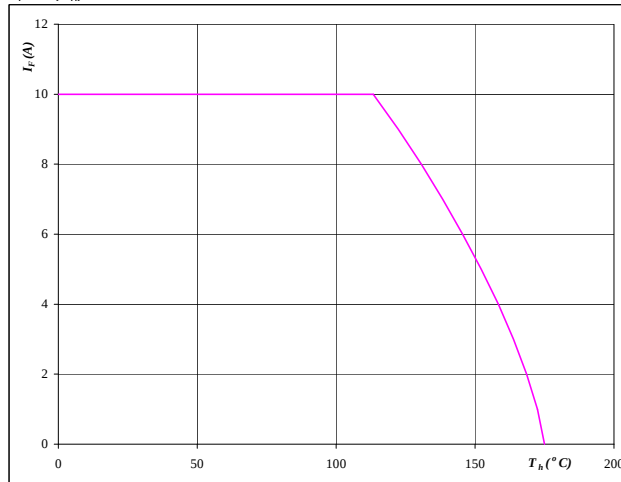


$T_J = 175^{\circ}\text{C}$

Figure 24 Output inverter FWD

Forward current as a
function of heatsink temperature

$$I_F = f(T_h)$$



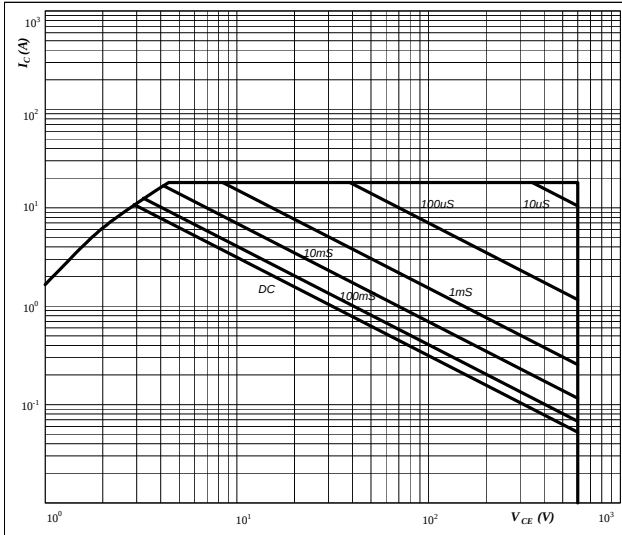
$T_J = 175^{\circ}\text{C}$

Output Inverter

Figure 25 Output inverter IGBT

Safe operating area as a function
of collector-emitter voltage

$$I_C = f(V_{CE})$$

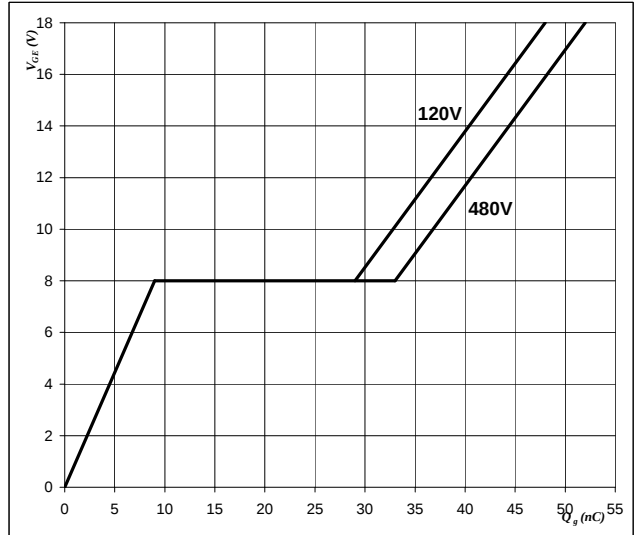


D = single pulse
T_h = 80 °C
V_{GE} = ±15 V
T_J = T_{Jmax} °C

Figure 26 Output inverter IGBT

Gate voltage vs Gate charge

$$V_{GE} = f(Q_{GE})$$

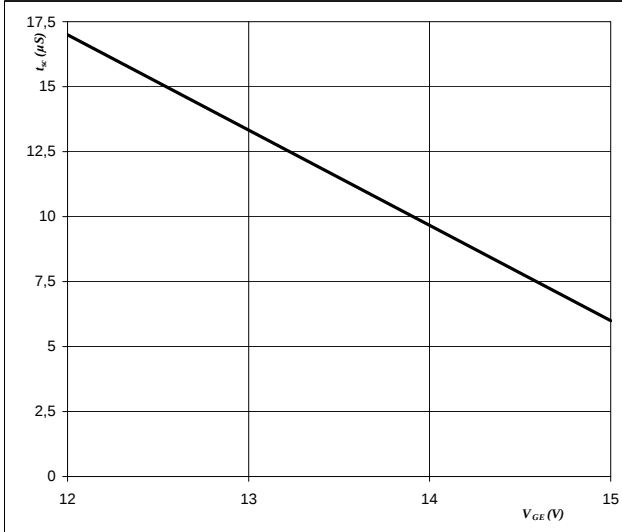


I_C = 6 A

Figure 27 Output inverter IGBT

Short circuit withstand time as a function of
gate-emitter voltage

$$t_{sc} = f(V_{GE})$$

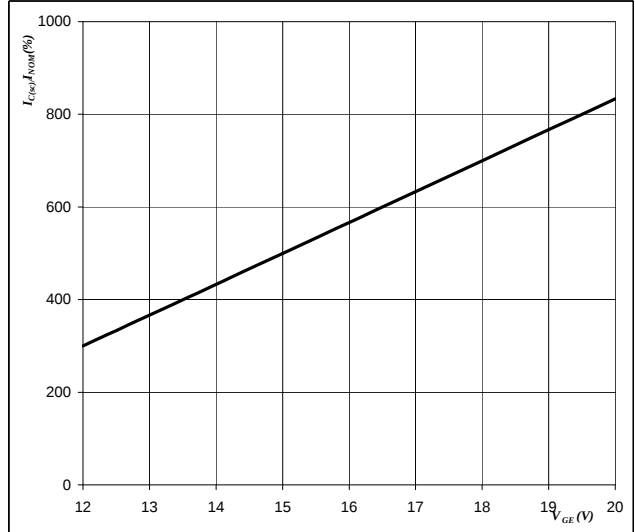


V_{CE} = 300 V
T_J ≤ 175 °C

Figure 28 Output inverter IGBT

Typical short circuit collector current as a function of
gate-emitter voltage

$$I_{sc} = f(V_{GE})$$



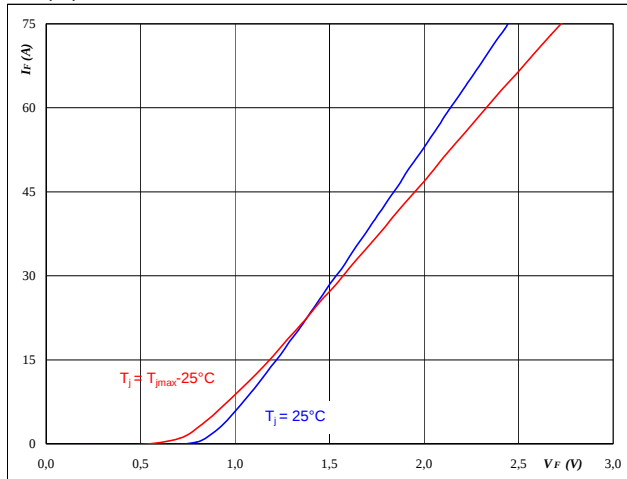
V_{CE} ≤ 300 V
T_J = 175 °C

Input Rectifier Bridge

Figure 1 Rectifier diode

Typical diode forward current as
a function of forward voltage

$$I_F = f(V_F)$$

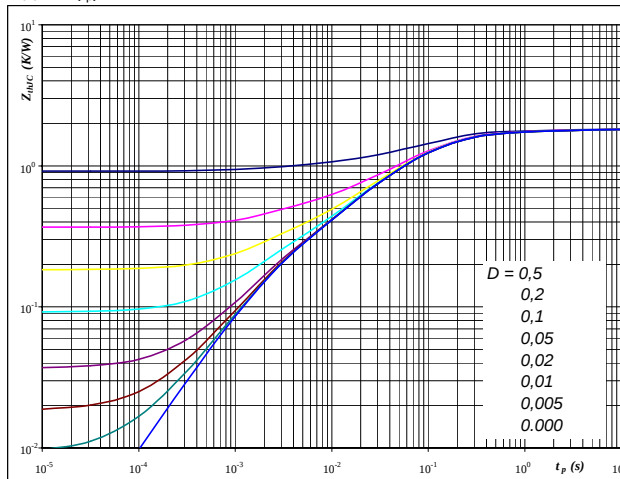


$t_p = 250 \mu s$

Figure 2 Rectifier diode

Diode transient thermal impedance
as a function of pulse width

$$Z_{thJH} = f(t_p)$$

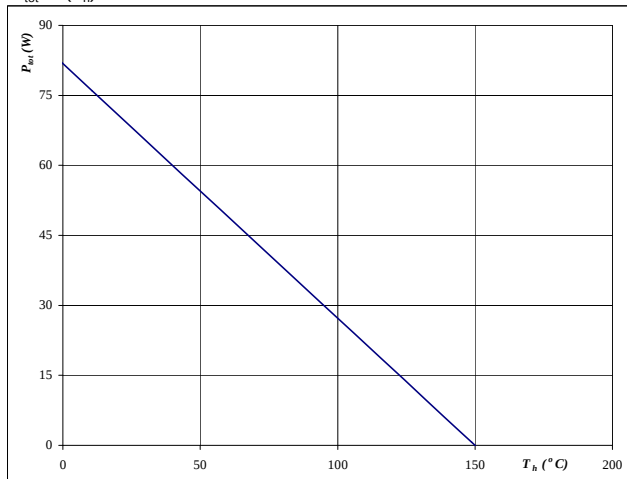


$D = t_p / T$
 $R_{thJH} = 1,834 \text{ K/W}$

Figure 3 Rectifier diode

Power dissipation as a
function of heatsink temperature

$$P_{tot} = f(T_h)$$

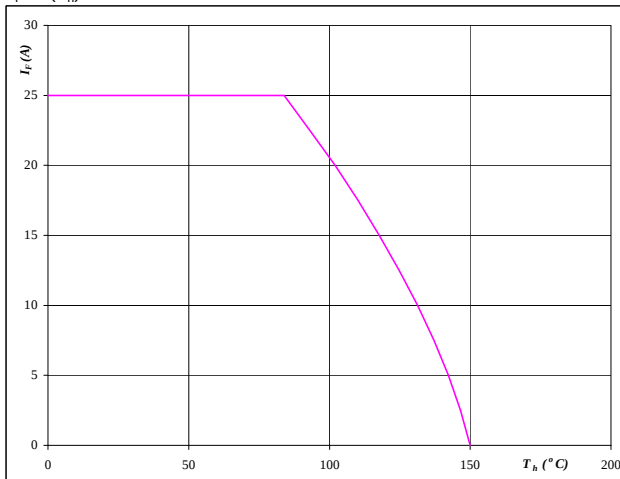


$T_j = 150 \text{ } ^\circ\text{C}$

Figure 4 Rectifier diode

Forward current as a
function of heatsink temperature

$$I_F = f(T_h)$$



$T_j = 150 \text{ } ^\circ\text{C}$

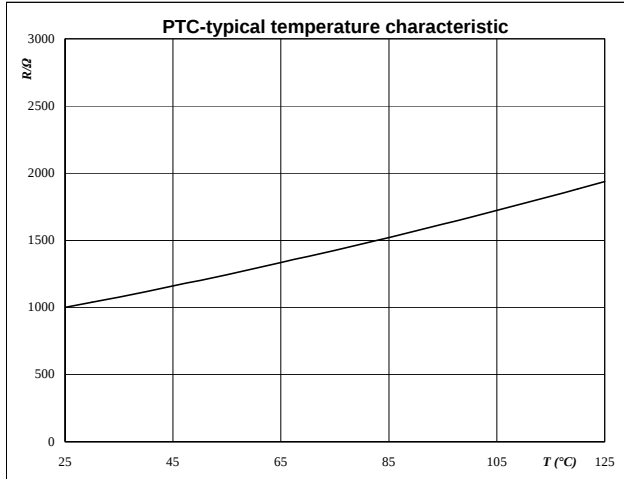
Thermistor

Figure 1

Thermistor

Typical PTC characteristic
as a function of temperature

$R_T = f(T)$



Thermistor

Equation of PTC resistance temperature dependency

$$R(T) = 1000 * [1 + A * (T - 25^{\circ}\text{C}) + B * (T - 25^{\circ}\text{C})^2] \quad [\Omega]$$

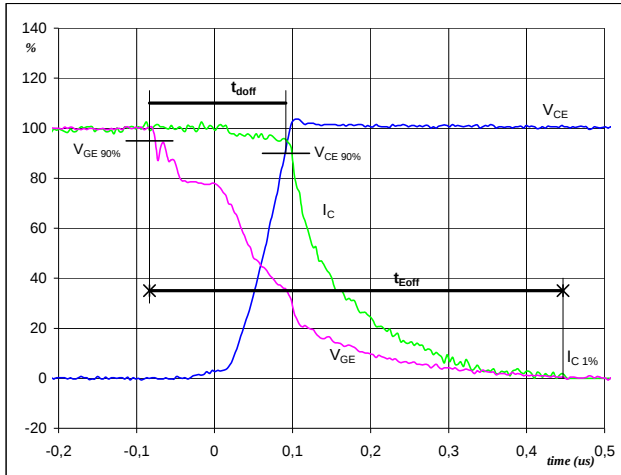
Switching Definitions Output Inverter

General conditions

T_j	=	150 °C
R_{gon}	=	64 Ω
R_{goff}	=	64 Ω

Figure 1 Output inverter IGBT

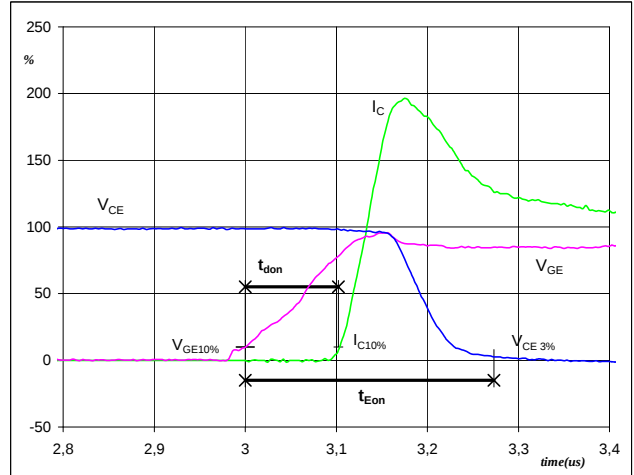
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
(t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$	=	-15	V
$V_{GE}(100\%)$	=	15	V
$V_C(100\%)$	=	300	V
$I_C(100\%)$	=	6	A
t_{doff}	=	0,16	μs
t_{Eoff}	=	0,53	μs

Figure 2 Output inverter IGBT

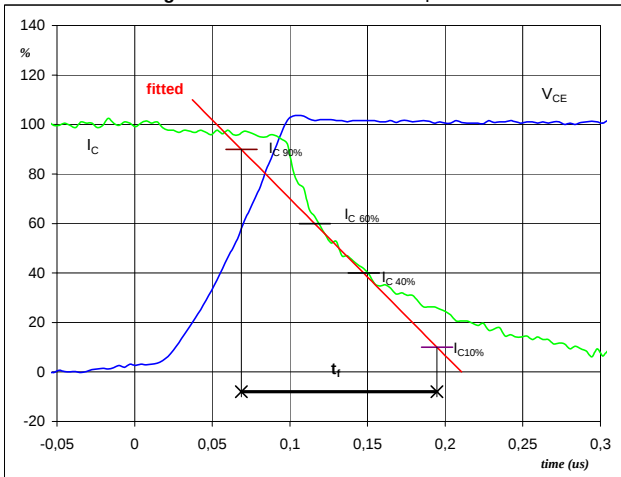
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}
(t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$	=	-15	V
$V_{GE}(100\%)$	=	15	V
$V_C(100\%)$	=	300	V
$I_C(100\%)$	=	6	A
t_{don}	=	0,10	μs
t_{Eon}	=	0,27	μs

Figure 3 Output inverter IGBT

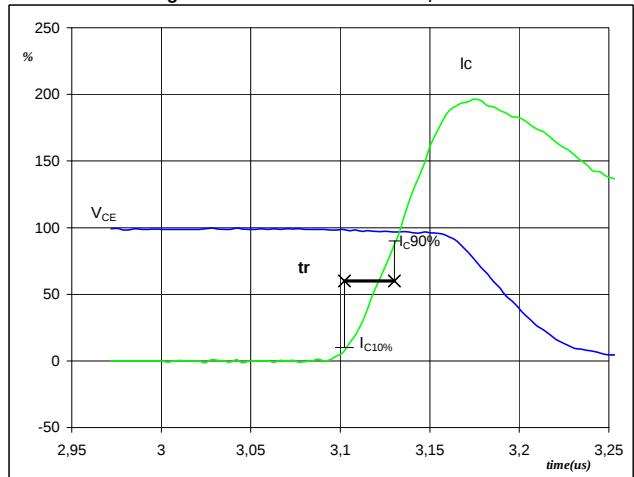
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$	=	300	V
$I_C(100\%)$	=	6	A
t_f	=	0,13	μs

Figure 4 Output inverter IGBT

Turn-on Switching Waveforms & definition of t_r

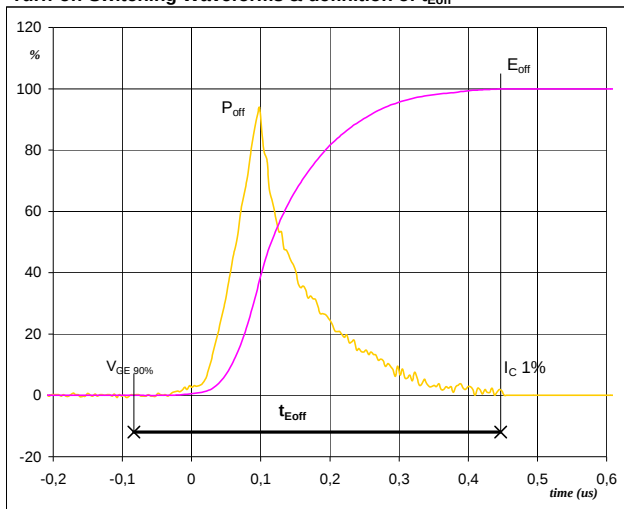


$V_C(100\%)$	=	300	V
$I_C(100\%)$	=	6	A
t_r	=	0,03	μs

Switching Definitions Output Inverter

Figure 5 Output inverter IGBT

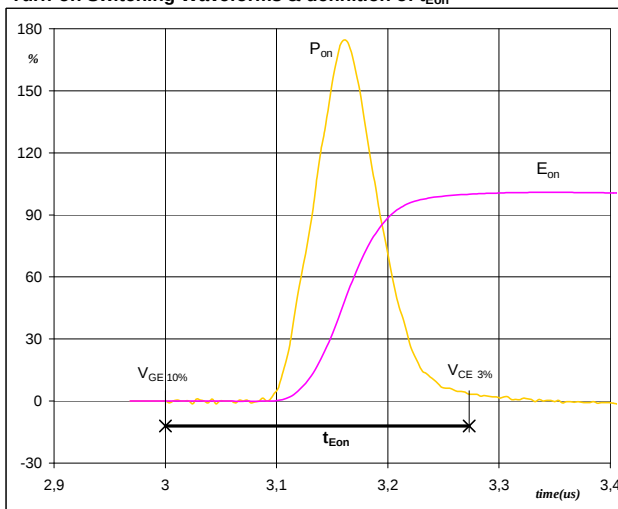
Turn-off Switching Waveforms & definition of t_{Eoff}



$P_{off} (100\%) = 1,80 \text{ kW}$
 $E_{off} (100\%) = 0,19 \text{ mJ}$
 $t_{Eoff} = 0,53 \text{ }\mu\text{s}$

Figure 6 Output inverter IGBT

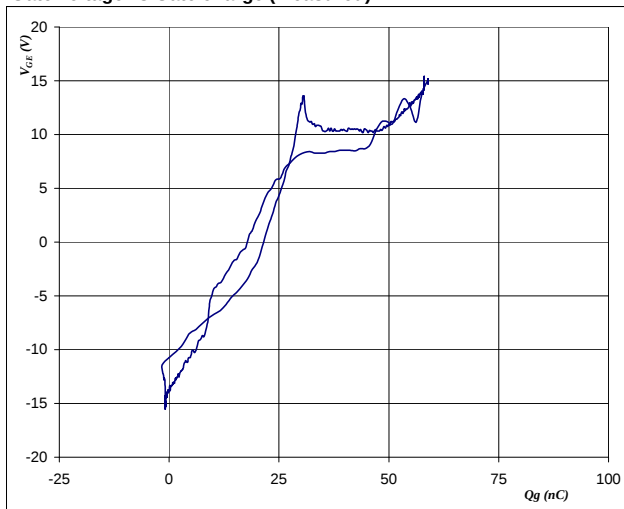
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on} (100\%) = 1,80 \text{ kW}$
 $E_{on} (100\%) = 0,23 \text{ mJ}$
 $t_{Eon} = 0,27 \text{ }\mu\text{s}$

Figure 7 Output inverter FWD

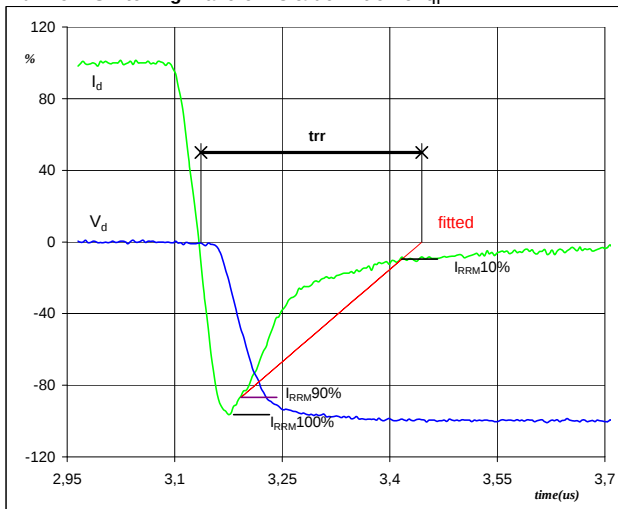
Gate voltage vs Gate charge (measured)



$V_{GEoff} = -15 \text{ V}$
 $V_{GEon} = 15 \text{ V}$
 $V_C (100\%) = 300 \text{ V}$
 $I_C (100\%) = 6 \text{ A}$
 $Q_g = 463,23 \text{ nC}$

Figure 8 Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{tr}

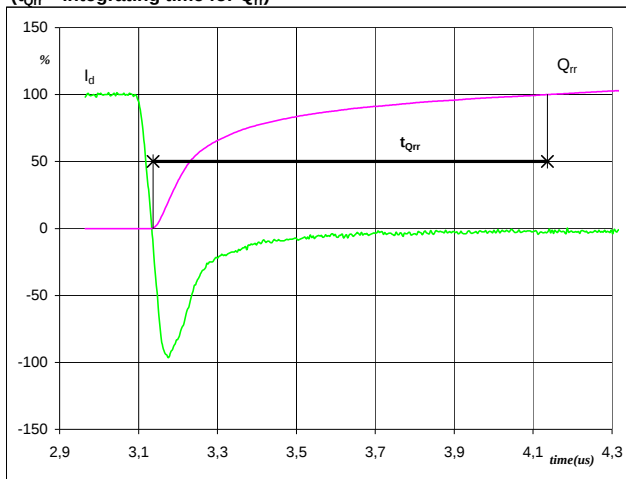


$V_d (100\%) = 300 \text{ V}$
 $I_d (100\%) = 6 \text{ A}$
 $I_{RRM} (100\%) = -6 \text{ A}$
 $t_{tr} = 0,29 \text{ }\mu\text{s}$

Switching Definitions Output Inverter

Figure 9 Output inverter FWD

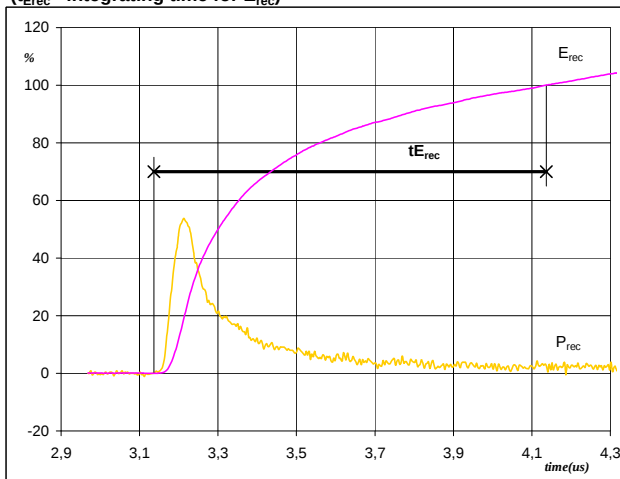
Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})



I_d (100%) = 6 A
 Q_{rr} (100%) = 0,78 μ C
 t_{Qrr} = 1,00 μ s

Figure 10 Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec} = integrating time for E_{rec})



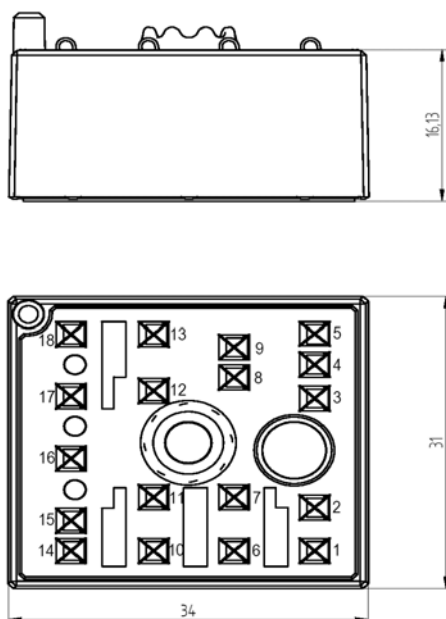
P_{rec} (100%) = 1,80 kW
 E_{rec} (100%) = 0,16 mJ
 t_{Erec} = 1,00 μ s

Ordering Code and Marking - Outline - Pinout

Ordering Code & Marking

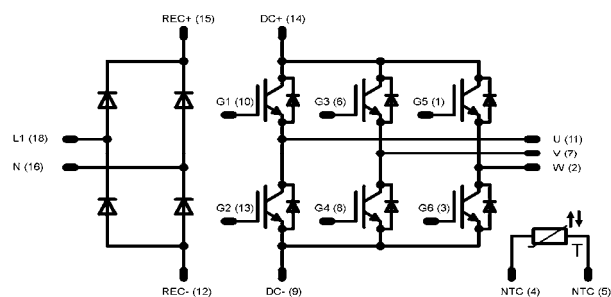
Version	Ordering Code	in DataMatrix as	in packaging barcode as
2-leg rectifier	80-M006PNB006SA01-K614D	K614D	K614D
3-leg rectifier	80-M006PNB006SA-K614C	K614C	K614C

Outline

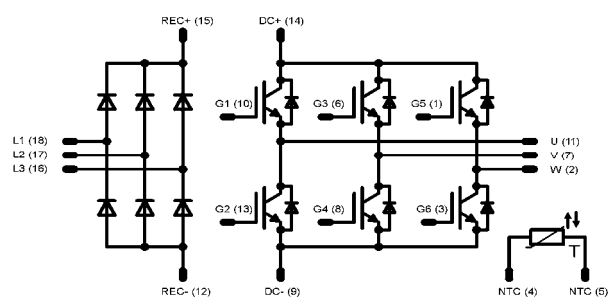


Pinout

for K61x-Dxx types



for K61x-Cxx types



PRODUCT STATUS DEFINITIONS

Datasheet Status	Product Status	Definition
Target	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. The data contained is exclusively intended for technically trained staff.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data may be published at a later date. Vincotech reserves the right to make changes at any time without notice in order to improve design. The data contained is exclusively intended for technically trained staff.
Final	Full Production	This datasheet contains final specifications. Vincotech reserves the right to make changes at any time without notice in order to improve design. The data contained is exclusively intended for technically trained staff.

DISCLAIMER

The information given in this datasheet describes the type of component and does not represent assured characteristics. For tested values please contact Vincotech. Vincotech reserves the right to make changes without further notice to any products herein to improve reliability, function or design. Vincotech does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

LIFE SUPPORT POLICY

Vincotech products are not authorised for use as critical components in life support devices or systems without the express written approval of Vincotech.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.